

FOR IMMEDIATE RELEASE



Frore Systems is keeping pace with NVIDIA in enabling AI Performance



SAN JOSE, California – December 23, 2024: NVIDIA's brand new 25 Watt ["little tiny Jetson Nano"](#) – the Jetson Orin Nano Super - capable of 67 trillion operations per second (TOPS) of AI performance, is going to generate a lot of heat that could limit its performance if the device isn't supported by adequate cooling.

Thanks to the high AI performance of the Jetson Orin Nano Super, breakthrough AI models such as NVIDIA Isaac™ for robotics, NVIDIA Metropolis for vision AI, and NVIDIA Holoscan for sensor processing, NVIDIA Omniverse™ Replicator for synthetic data generation (SDG) and NVIDIA TAO Toolkit for fine-tuning pretrained AI models may now run at the Edge, delivering compute efficiency, reduced latency and data privacy. But without adequate heat dissipation, the Jetson Orin Nano Super will be forced to throttle, significantly reducing its performance and diminishing the capabilities of Edge AI applications supported including robotics, industrial automation, smart cities, healthcare, and retail analytics.

AirJet®PAK 5C-25 from Frore Systems, can provide the full 25 Watts of cooling NVIDIA's Jetson Orin Nano Super needs. The AirJet®PAK 5C-25 is a fully self-contained, autonomous, plug and play, solid-state active cooling thermal module, that is thin, silent, dustproof, water resistant, and enables the full performance of the Jetson Nano Super, even in the toughest operating conditions. The AirJet PAK®5C-25 can be combined with the Jetson Orin Nano Super to remove 25 Watts of heat, even in industrial grade casings that are ultra compact, silent, vibration free, dustproof and water-resistant. These industrial grade casings, enabled by the AirJet®PAK, are massively smaller and lighter than comparable fanless casings that require large, heavy heat sinks to dissipate heat. Of course, sometimes, fan-based cooling solutions are used, but mechanical fans have serious disadvantages, creating noise and requiring device casings with holes that actively pull dust and moisture into the device, limiting lifetime, reliability and performance. The AirJet PAK®5C-25 based solution is so compact that it is 60% smaller than even these fan-based alternatives.

The AirJet PAK, is the world's first solid-state active cooling solution designed to complement a wide range of System on Module (SoM) AI Computers, including NVIDIA's Jetson Orin Nano, Nano Super, NX & Orin AGX modules, as well as SoMs from Qualcomm, NXP, AMD/Xilinx, and more. The AirJet PAK can be directly mounted on the SoM, removing heat and unleashing the full Edge AI performance.

AirJet PAKs are available in a range of sizes designed for easy integration into EDGE AI platforms of varying performance requirements.

* AirJet®PAK 5C-25: contains 5 AirJet chips, measures just 100x65x9.8mm, removes up to 25 Watts of heat, and supports up to 100 TOPS.

* AirJet®PAK 3C-15: contains 3 AirJet chips, measures just 100x65x5.8mm, removes up to 15 Watts of heat, and supports up to 40 TOPS.

* AirJet®PAK 1C-5: contains 1 AirJet chip, measures just 30x65x5mm, removes up to 5 Watts of heat, and supports up to 10 TOPS.

Like all AirJet products, the AirJet PAK is easily scalable, multiple AirJet PAKs can be combined when higher levels of processor performance and heat dissipation is needed. For example, 2 AirJet®PAK 5C-25 can be used to remove up to 50 Watts of heat supporting up to 200 TOPS.

Frore Systems will be at CES in January 2025 giving everyone the opportunity to see the technology in action, with live demonstrations of Industrial Edge AI platforms with AirJet PAK, consumer products upgraded with AirJet delivering significantly higher performance, including Samsung Galaxy Book4 Edge, MacBook Air, iPad Pro, Premium Smartphone and SSD accessory. Also, we are showcasing several commercial products with AirJet that are already shipping. Frore System's groundbreaking products unlock the performance needed for Edge AI devices.

Experience the future of AI performance and more, in the Frore Systems Demonstration Room, January 7 – 10 in Las Vegas, at the Venetian Expo on Level 2, in Room 2401B.

About Frore Systems

Frore Systems is the developer of breakthrough thermal technology for electronic and consumer devices. The company's active cooling solutions, the AirJet®Mini, AirJet®Mini Slim, AirJet®Mini Sport, and AirJet®PAKs, are integrated into devices to remove heat silently, resulting in major performance gains and enabling thinner, lighter, silent, vibration free, dustproof and waterproof devices. Frore Systems is headquartered in San Jose, CA with an office and manufacturing facility in Taiwan. For more information, please visit <https://froresystems.com/>

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